

AMENDMENTS TO THE CLAIMS

The listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Previously Presented) A shielded probe apparatus for testing a semiconductor device, comprising:
 - a shielded probe for probing the semiconductor device;
 - a tri-axial cable coupled to a test equipment;
 - a shielded chassis; and
 - the tri-axial cable and the shielded probe being configured and arranged to connect to each other within the shielded chassis;
 - wherein the tri-axial cable comprises:
 - a center signal conductor;
 - a dielectric layer, the center signal conductor being surrounded by the dielectric layer;
 - a conductive layer, the dielectric layer being surrounded by the conductive layer;
 - a guard layer, the conductive layer being surrounded by the guard layer;
 - a second dielectric layer, the guard layer being surrounded by the second dielectric layer;
 - a shield, the second dielectric layer being surrounded by the shield; and
 - a protective cover, the shield being surrounded by the protective cover
 - wherein the guard layer is driven to the same potential as the center signal conductor, and the shield is grounded to the shielded chassis.
2. (Original) The apparatus of claim 1, wherein the shielded probe comprises:
 - a probe pin;
 - a dielectric layer, the probe pin being surrounded by the dielectric layer; and
 - a conductive guard layer, the dielectric layer being surrounded by the conductive guard layer.

Claim 3 (Canceled).

4. (Original) The apparatus of claim 2, wherein the shielded probe further comprises a second dielectric layer, the conductive guard layer being surrounded by the second dielectric layer.

5. (Previously Presented) The apparatus of claim 2, wherein the probe pin and the center signal conductor are electrically connected to each other.

6. (Original) The apparatus of claim 5, wherein the probe pin is connected to the center signal conductor by soldering/brazing the probe pin on the center signal conductor.

7. (Original) The apparatus of claim 5, further comprising a shrink tube to shrink-tube the probe pin and the center signal conductor.

8. (Previously Presented) The apparatus of claim 2, wherein the conductive guard layer of the shielded probe and the guard layer of the tri-axial cable are electrically connected to each other.

9. (Original) The apparatus of claim 8, further comprising a second shrink tube to shrink-tube the conductive guard layer and the guard layer.

Claim 10 (Canceled).

11. (Currently Amended) A shielded probe apparatus, capable of electrically testing a semiconductor device at a sub 100fA operating current and an operating temperature up to 300C, comprising:

a shielded probe having a shielded chassis; and
a tri-axial cable having a center signal conductor, a guard layer, and a shield, wherein the shielded probe and the tri-axial cable that are electrically connected within a the shielded chassis;

wherein the guard layer of the tri-axial cable is driven to the same potential as the center signal conductor, and the shield of the tri-axial cable is grounded to the shielded chassis.

12. (Original) The apparatus of claim 11, wherein the shielded probe comprises:
a probe pin;
a dielectric layer, the probe pin being surrounded by the dielectric layer; and
a conductive guard layer, the dielectric layer being surrounded by the conductive guard layer.

Claim 13 (Canceled).

14. (Original) The apparatus of claim 12, wherein the shielded probe further comprises a second dielectric layer, the conductive guard layer being surrounded by the second dielectric layer.

15. (Currently Amended) The apparatus of claim 13, wherein the probe pin and the center signal conductor are electrically connected to each other.

16. (Original) The apparatus of claim 15, wherein the probe pin is connected to the center signal conductor by soldering/brazing the probe pin on the center signal conductor.

17. (Original) The apparatus of claim 15, further comprising a shrink tube to shrink-tube the probe pin and the center signal conductor.

18. (Currently Amended) The apparatus of claim 13, wherein the conductive guard layer of the shielded probe and the guard layer of the tri-axial cable are electrically connected to each other.

19. (Original) The apparatus of claim 18, further comprising a second shrink tube to shrink-tube the conductive guard layer and the guard layer.

Claim 20 (Canceled).